

Schottky Barrier Diodes

BAT54XV2

These Schottky barrier diodes are designed for high-speed switching applications, circuit protection, and voltage clamping. Extremely low forward voltage reduces conduction loss. Miniature surface mount package is excellent for hand-held and portable applications where space is limited.

Features

- Extremely Fast Switching Speed
- Low Forward Voltage – 0.35 V (Typ) @ $I_F = 10$ mA
- S Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

MAXIMUM RATINGS ($T_J = 125^\circ\text{C}$ unless otherwise noted)

| Rating | Symbol | Value | Unit |
|-----------------|--------|-------|------|
| Reverse Voltage | V_R | 30 | V |

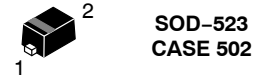
THERMAL CHARACTERISTICS

| Characteristic | Symbol | Max | Unit |
|---|-----------------|------------|----------------------------|
| Total Device Dissipation FR-5 Board, (Note 1) $T_A = 25^\circ\text{C}$ Derate above 25°C | P_D | 200 2.0 | mW mW/ $^\circ\text{C}$ |
| Forward Current (DC) | I_F | 200 Max | mA |
| Non-Repetitive Peak Forward Current, $t_p < 10$ msec | I_{FSM} | 600 | mA |
| Repetitive Peak Forward Current Pulse Wave = 1 sec, Duty Cycle = 66% | I_{FRM} | 300 | mA |
| Thermal Resistance, Junction-to-Ambient | $R_{\theta JA}$ | 635 | $^\circ\text{C}/\text{W}$ |
| Junction and Storage Temperature | T_J, T_{stg} | -55 to 125 | $^\circ\text{C}$ |

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. FR-4 Minimum Pad.

30 VOLT SILICON HOT-CARRIER DETECTOR AND SWITCHING DIODES



MARKING DIAGRAM



- JV = Device Code
- M = Date Code*
- = Pb-Free Package

(Note: Microdot may be in either location)

*Date Code orientation may vary depending upon manufacturing location.

ORDERING INFORMATION

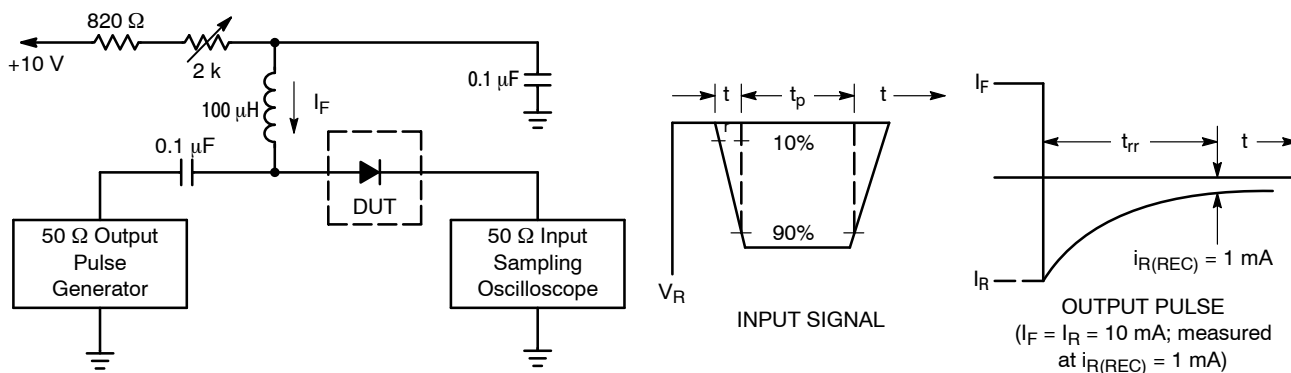
| Device | Package | Shipping† |
|--------------|-------------------|--------------------|
| BAT54XV2T1G | SOD-523 (Pb-Free) | 3000 / Tape & Reel |
| BAT54XV2T5G | SOD-523 (Pb-Free) | 8000 / Tape & Reel |
| SBAT54XV2T1G | SOD-523 (Pb-Free) | 3000 / Tape & Reel |
| SBAT54XV2T5G | SOD-523 (Pb-Free) | 8000 / Tape & Reel |

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

BAT54XV2

ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ unless otherwise noted)

| Characteristic | Symbol | Min | Typ | Max | Unit |
|---|-------------|-----|--------------------------------------|--------------------------------------|---------------|
| Reverse Breakdown Voltage ($I_R = 10 \mu\text{A}$) | $V_{(BR)R}$ | 30 | - | - | V |
| Total Capacitance ($V_R = 1.0 \text{ V}$, $f = 1.0 \text{ MHz}$) | C_T | - | 7.6 | 10 | pF |
| Reverse Leakage ($V_R = 25 \text{ V}$) | I_R | - | 0.3 | 2.0 | μA |
| Forward Voltage ($I_F = 0.1 \text{ mA}$) ($I_F = 1.0 \text{ mA}$) ($I_F = 10 \text{ mA}$) ($I_F = 30 \text{ mA}$) ($I_F = 100 \text{ mA}$) | V_F | - | 0.22 0.28 0.35 0.39 0.46 | 0.24 0.32 0.40 0.50 0.80 | V |
| Reverse Recovery Time ($I_F = I_R = 10 \text{ mA}$, $I_{R(\text{REC})} = 1.0 \text{ mA}$) Figure 1 | t_{rr} | - | - | 5.0 | ns |



- Notes: 1. A 2.0 k Ω variable resistor adjusted for a Forward Current (I_F) of 10 mA.
 2. Input pulse is adjusted so $I_{R(\text{peak})}$ is equal to 10 mA.
 3. $t_p \gg t_{rr}$

Figure 1. Recovery Time Equivalent Test Circuit

BAT54XV2

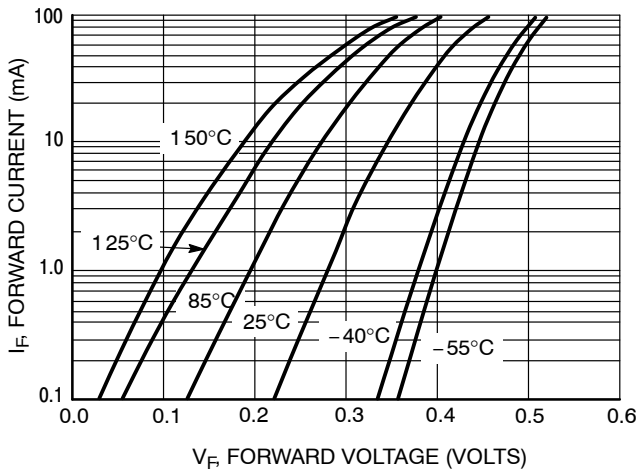


Figure 2. Forward Voltage

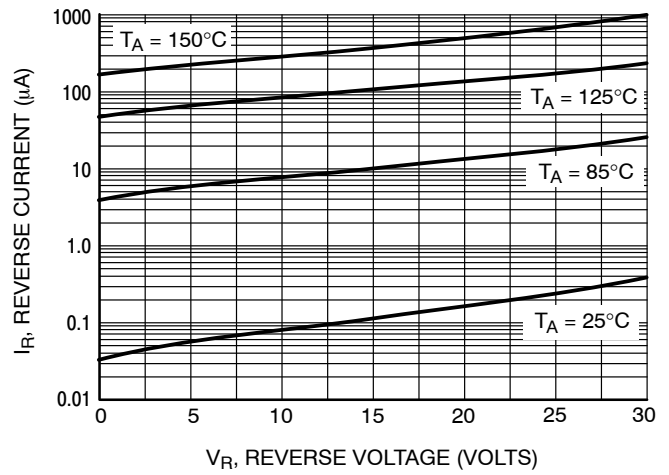


Figure 3. Leakage Current

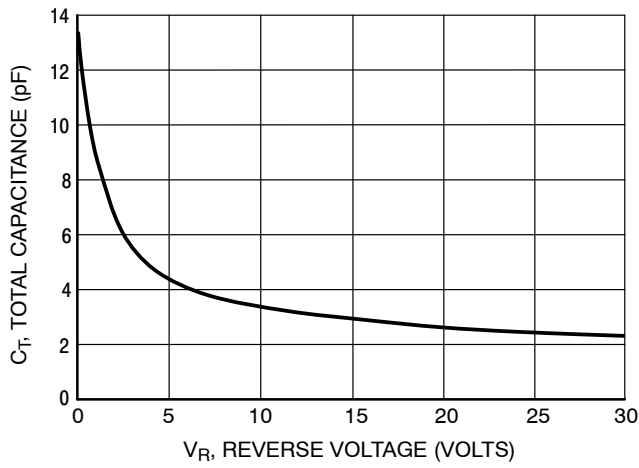


Figure 4. Total Capacitance

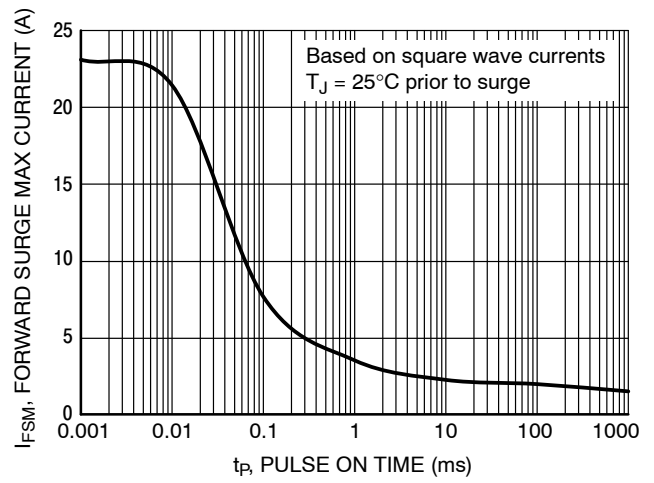


Figure 5. Forward Surge Current

MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

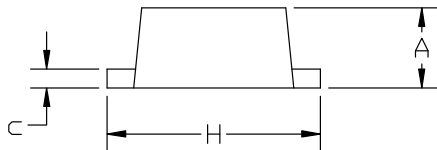


SOD-523 1.20x0.80x0.60
CASE 502
ISSUE F

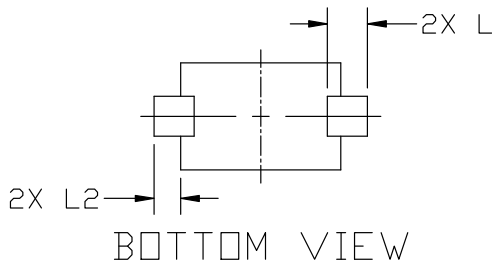
DATE 08 FEB 2024



TOP VIEW



SIDE VIEW

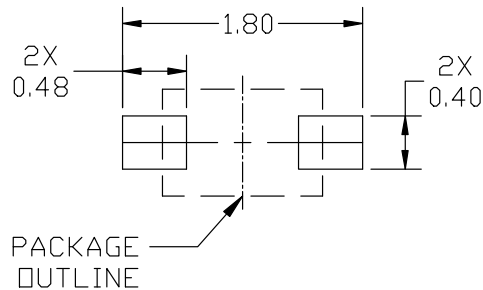


BOTTOM VIEW

NOTES:

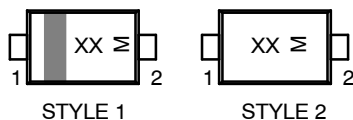
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2018.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH, MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

| DIM | MILLIMETERS | | |
|-----|-------------|------|------|
| | MIN. | NOM. | MAX. |
| A | 0.50 | 0.60 | 0.70 |
| b | 0.25 | 0.30 | 0.35 |
| c | 0.07 | 0.14 | 0.20 |
| D | 1.10 | 1.20 | 1.30 |
| E | 0.70 | 0.80 | 0.90 |
| H | 1.50 | 1.60 | 1.70 |
| L | 0.30 REF | | |
| L2 | 0.15 | 0.20 | 0.25 |



RECOMMENDED MOUNTING FOOTPRINT

GENERIC MARKING DIAGRAM*



XX = Specific Device Code
M = Date Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

STYLE 1: PIN 1. CATHODE (POLARITY BAND) 2. ANODE
STYLE 2: NO POLARITY

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference manual, SOLDERRM/D.

| | | |
|-------------------------|-------------------------------|--|
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| DESCRIPTION: | SOD-523 1.20x0.80x0.60 | PAGE 1 OF 1 |

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